

Dismantling information

The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of LG products to remove components and materials requiring selective treatment.

Product Identification

Type of Product	Monitor
Model name	32G620B This document covers derivation model which has same conceptual design and dismantling process

Displays must be stored in accordance with the requirements stipulated in Appendix VII (1) or (2) of Directive 2012/19/EU and must, amongst other things, be stored in a weatherproof manner. Containers with covers must be used when storing and transporting the Displays.

Contents

- 1. Materials and components for Selective Treatment**
- 2. Tools Required**
- 3. Product Disassembly Process**
- 4. Disassembly of External enclosure**

1. Materials and components for Selective Treatment

Displays may contain hazardous substances like Pb which are covered by exemptions under the RoHS directive. However, the majority is present in the PCB assembly. In order to reduce emissions as much as possible, a complete disposal of the old appliance is required. This treatment may only be performed in authorized handling plants.

Materials and components	Notes	Included	Location
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)		O	
Batteries	For Remote control	-	
	Internal batteries	-	
Mercury containing components	display backlights	-	
Liquid Crystal Displays (LCD) with a surface greater than 100 square cm	Includes background illuminated displays with gas discharge lamps	O	
Capacitors / condensers (Containing PCB / PCT)		-	
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		-	
External electric cables cords	Power cord	-	Following outgoing suffix
	Signal cable	O	
Gas Discharge Lamps		-	
Plastics containing Brominated Flame Retardants	Plastic of speaker, cable connector, fan (depend on model)	-	
Components and waste containing asbestos		-	
Components, parts and materials containing refractory ceramic fibers		-	
Components, parts and materials containing radioactive substances		-	

2. Tools Required

List the type that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool information
Screw driver	 
Nipper	
Plastic Hera Jig	

3. Product Disassembly Process

1) Batteries

Batteries can easily be removed from the remote control once the back cover of the remote control has been removed.

No
Battery

Batteries can easily be removed from the PCB Assembly once the back cover of product has been removed.

No Battery

3. Product Disassembly Process

2) PCBs

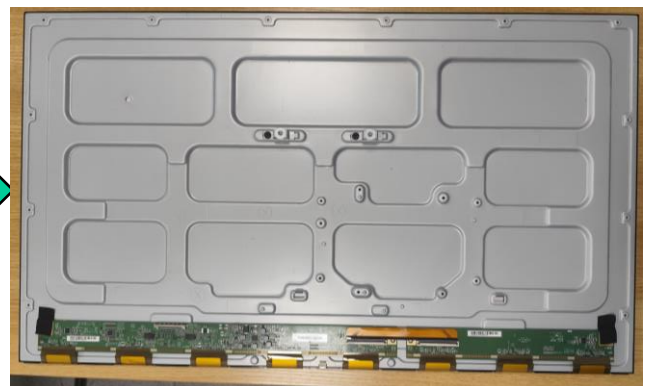
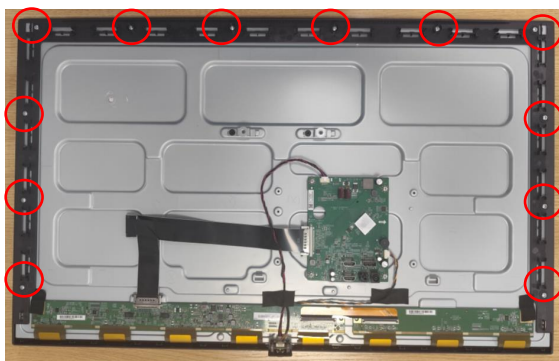
Unscrew and disassemble the back cover and disconnect the key connector.



Remove all the tape and wire, can and remove the main board



Unscrew the screws middle front.



3. Product Disassembly Process

2) PCBs

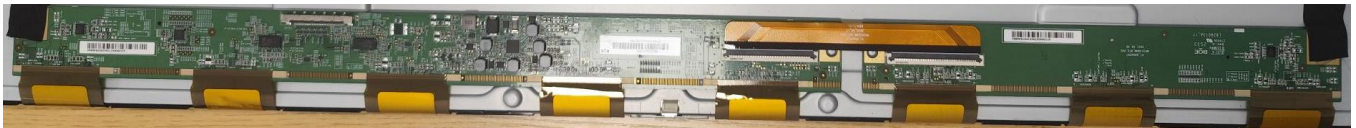


Module PCB

Control Board



LCD module



3. Product Dismantling Process

3) Plastics containing Brominated Flame Retardants

Plastic of speaker, fan, cable connector may contain brominated flame retardants, remove them all using a common available tool.

4) LCD Module

LCD (together with their casing) is only left after all other parts like electronic units have been removed.

LCD module



3. Product Disassembly Process

5) Power cord and signal cables

A Power cord plugged into the back of the display can easily be removed by hand or cables are provided as de-attached from the product



Adapter, DP cable

6) Capacitors > 25 mm (N/A)

Capacitors > 25 mm are located in the power supply units and can be removed by nipper : **doesn't exist (Cap size is under 25mm)**



4. Disassembly of External enclosure

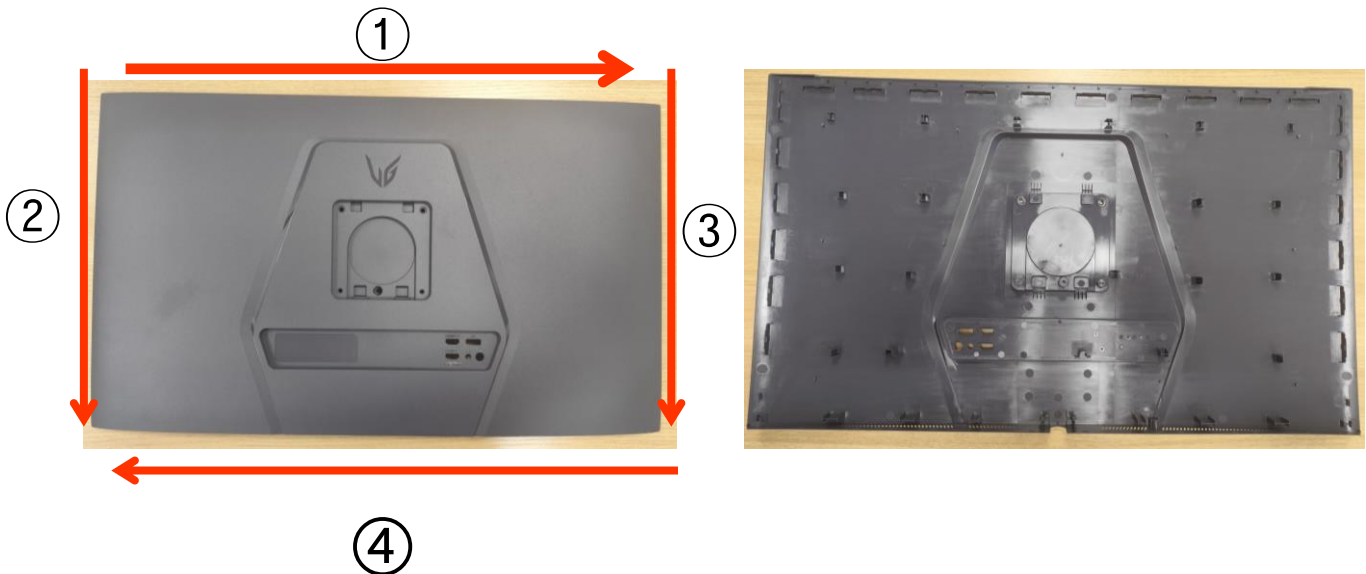
Push the base lock upwards as shown by the red circle, and push the base body upwards as shown in the blue arrow to remove the base body and base.



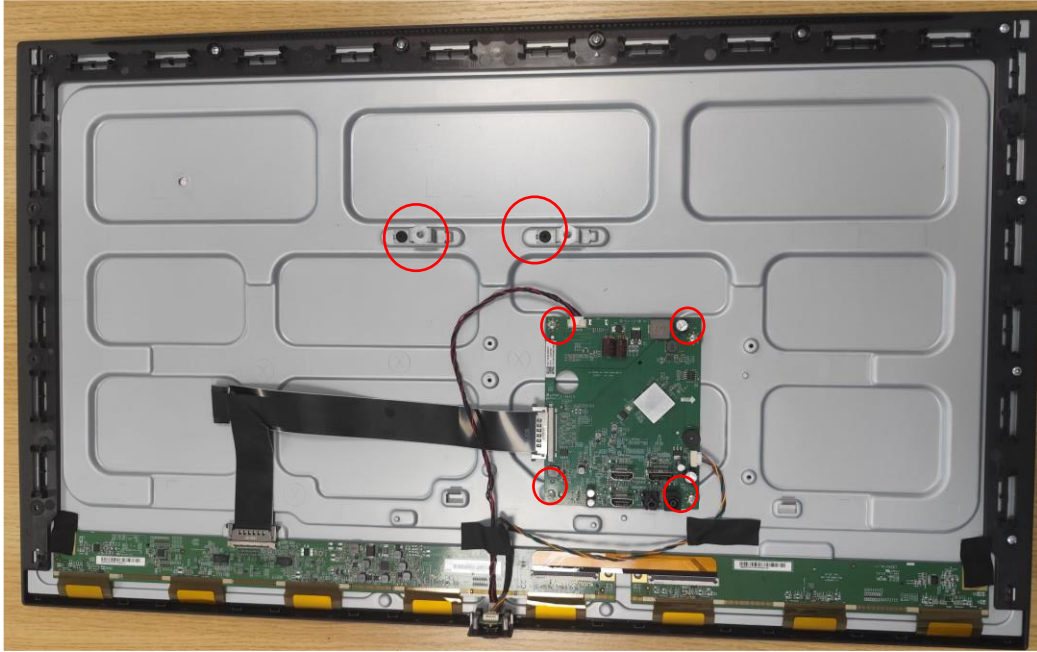
Remove the 3ea rear shell screws



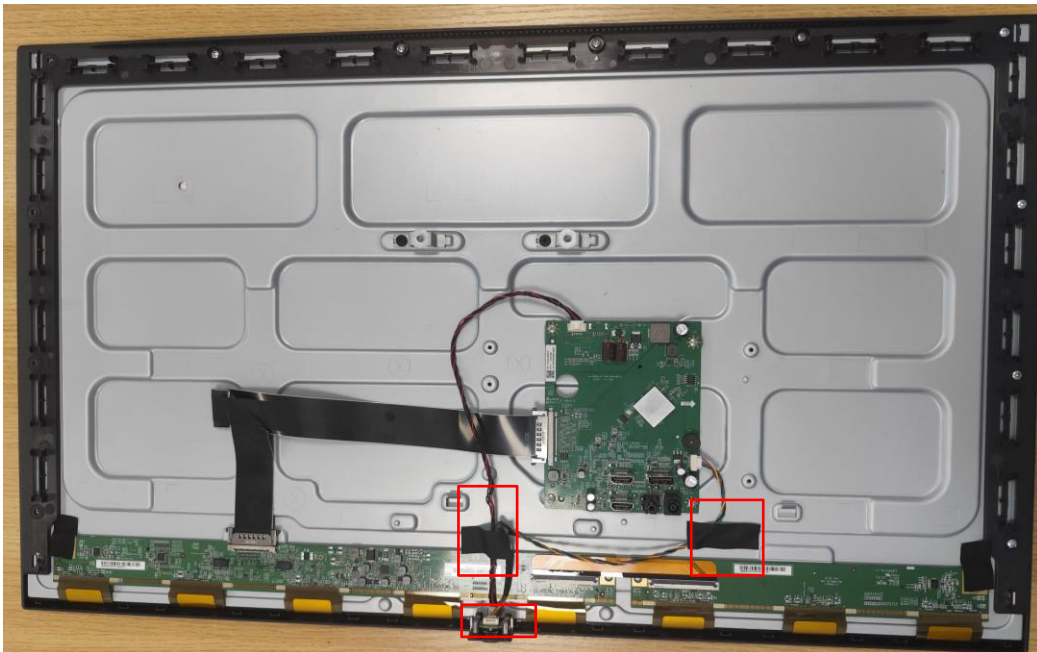
Take the disassembling knife, cut the back shell along the joint between the back shell and the front frame, and remove the back shell



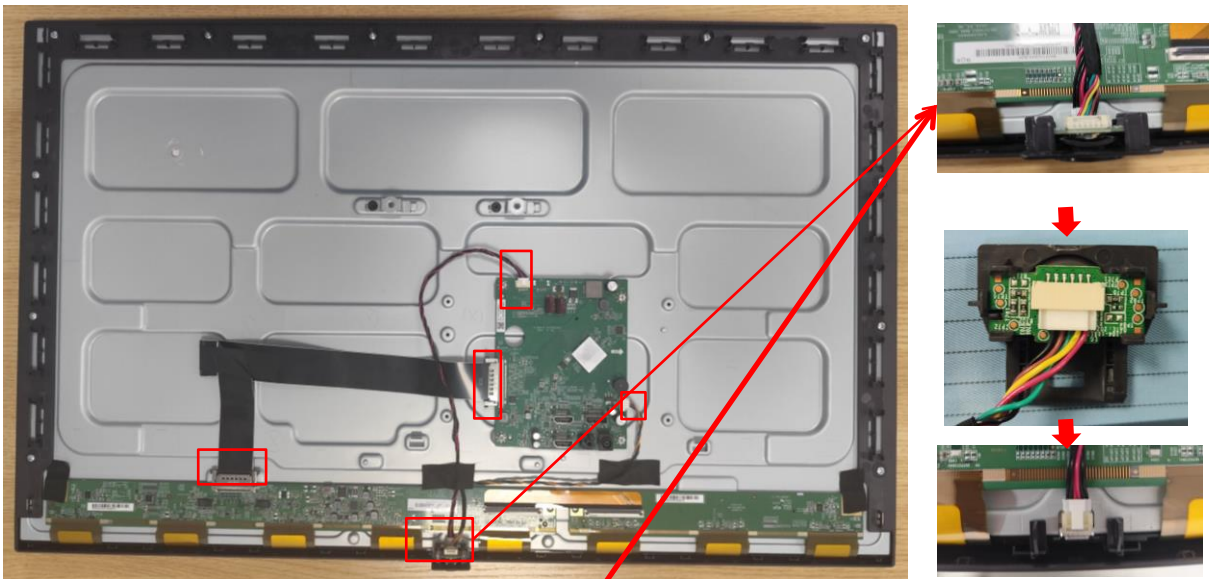
Take the screwdriver, remove the wall mounting screws *2ea, motherboard screws *4ea



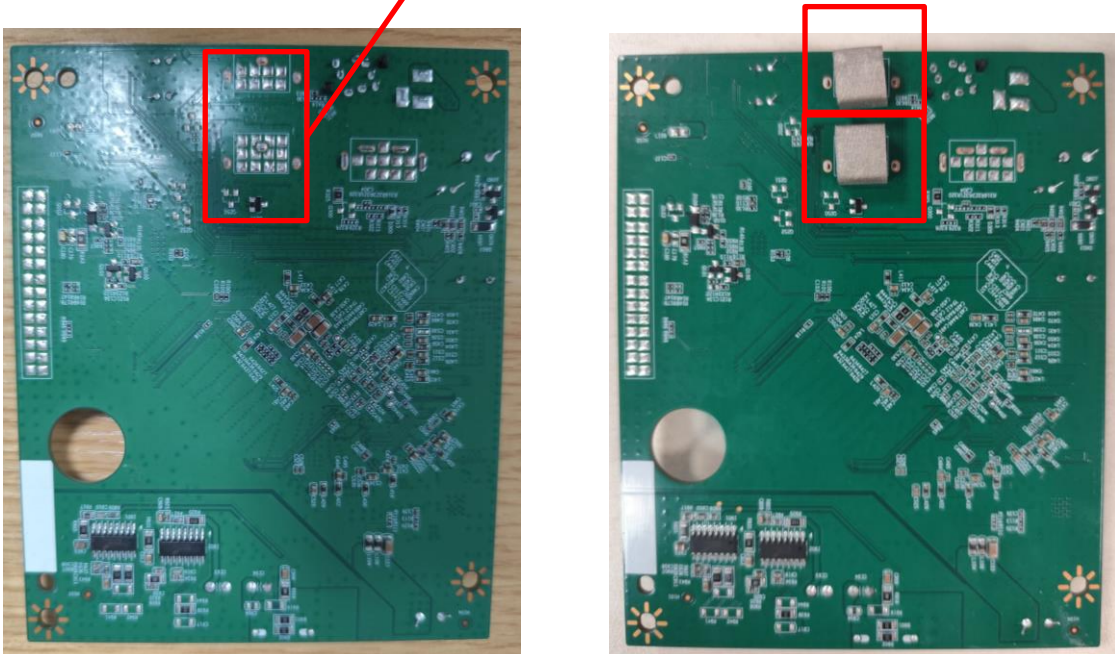
Peel acetate tape, as shown in the red box, and remove the wall hangings



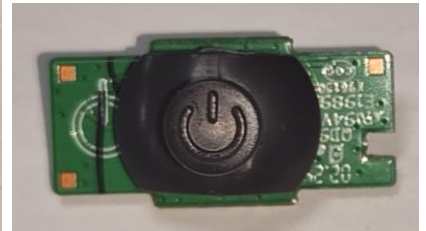
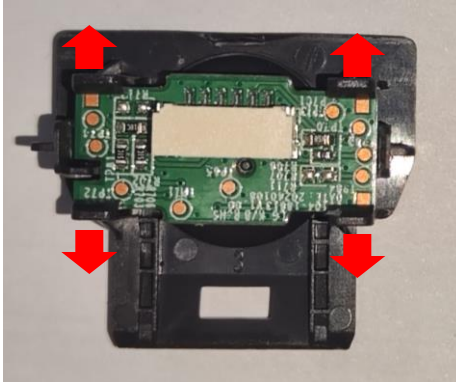
Remove the LVDS cable, button cable and backlight cable, as shown in the red box, and remove the motherboard



Remove the conductive foam on the back of the mainboard, as shown in the red box



Take the function key combination, break the card hook to both sides, remove the key and the key pad, and then separate the key and the key pad



Remove the center frame screw *15ea, and then remove the center frame

